

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YUKI KAWANA	06/05/2021
HIDEO NAKAKO	05/27/2021
MOTOHIRO NEGISHI	05/31/2021
CHIE SUGAMA	05/27/2021
YOSHINORI EJIRI	05/31/2021
YUICHI YANAKA	06/01/2021
RECEIVING PARTY DATA	
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17296986
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NAME OF SUBMITTER:	BELINDA LEE
SIGNATURE:	/Belinda Lee/
DATE SIGNED:	06/20/2021
Total Attachments: 2	

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ASSIGNMENT

Whereas, I/we,

<u>Name</u>	<u>Address</u>
1) <u>Yuki KAWANA</u>	c/o Showa Denko Materials Co., Ltd., 9-2, Marunouchi 1-chome, Chiyoda-ku, Tokyo 100-6606 Japan
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5) <u>Yoshinori EJIRI</u>	c/o Showa Denko Materials Co., Ltd., 9-2, Marunouchi 1-chome, Chiyoda-ku, Tokyo 100-6606 Japan
6) <u>Yuichi YANAKA</u>	c/o Showa Denko Materials Co., Ltd., 9-2, Marunouchi 1-chome, Chiyoda-ku, Tokyo 100-6606 Japan

hereinafter called assignor(s), have invented certain improvements in
METHOD FOR PRODUCING BONDED OBJECT AND SEMICONDUCTOR DEVICE AND COPPER BONDING PASTE

and executed an application for Letters Patent of the United States of America therefor on even date herewith unless otherwise indicated below:

filed on May 26, 2021, Serial No. 17 / 296986; and

Whereas

Showa Denko Materials Co., Ltd.
 9-2, Marunouchi 1-chome,
 Chiyoda-ku, Tokyo 100-6606 Japan

(assignee), desires to acquire the entire right, title and interest in the application and invention, and to any United States patents to be obtained therefor;

NOW THEREFORE, be it known that, for good and valuable consideration from assignee, the receipt of which is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

In the event that the patent application filing date or serial number is not known at the time this Assignment is executed, I/WE hereby grant permission to the attorneys of record in the patent application to fill in the filing date and/or serial number above, and to record this Assignment after such information is added.

	<u>INVENTORS</u>	<u>DATE SIGNED</u>
1):	<u>Yuki Kawana</u>	<u>06.05.2021</u>
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2):	<u>Hideo Nataka</u>	<u>May 29, 2021</u>
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